

Title (en)

STACK OF LASER DIODES FORMING A LASER DEVICE

Title (de)

EINE LASERVORRICHTUNG BILDENDER LASERDIODENSTAPEL

Title (fr)

DISPOSITIF LASER FORME PAR UN EMPILEMENT DE DIODES LASER

Publication

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Application

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Abstract (en)

[origin: WO2006122691A2] The laser device (22) is formed by a stack of laser diodes (4) placed on wafers (6) made of an electrically conductive material and having a good heat conductivity. In order to obtain a good efficiency in the evacuation of heat toward the cooling body (10) and to avoid the problems associated with an electrical short circuit, each wafer has, on its lower end (24), an electrically non-conductive layer placed on its surface before fastening to the cooling body by a fastening material (26) that preferably conducts heat well, formed, in particular, by a solder layer. According to the invention, the non-conductive layer has a width that is sufficient for enabling the fastening material to partially cover the lateral sides of the non-conductive layers, and the fastening material extends between the wafers, i.e. so that it forms a continuous layer on the cooling body.

IPC 8 full level

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